

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	BSB104N08NP3 G	**Issued**	27. April 2022
MA#	MA005737800		
Package	MG-WDSON-2-6	**Weight***	79.78 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.759	3.46	3.46	34582	34582
leadframe	non noble metal	copper	7440-50-8	74.415	93.29	93.29	932805	932805
leadfinish	non noble metal	nickel	7440-02-0	0.211	0.26		2647	
	noble metal	silver	7440-22-4	0.840	1.05	1.31	10530	13177
plating	non noble metal	nickel	7440-02-0	0.211	0.26	0.26	2647	2647
glue	miscellaneous	miscellaneous	-	0.017	0.02		216	
	plastics	acrylic resin	-	0.135	0.17		1687	
	noble metal	silver	7440-22-4	0.860	1.08	1.27	10782	12685
passivation	plastics	epoxy resin	-	0.327	0.41	0.41	4104	4104
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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